

# Single Wafer Wet Processing System

## TWP Series



Automatic Type

- High stripping performance
- TAKADA proprietary jet-liftoff
- Multiple processes in one chamber, such as liftoff, stripping and cleaning in one chamber

# TAKADA Wet Processor

## Applications

- ◆ Lifftoff and resist stripping processes for MEMS, LED, high frequency devices

## Features

- Multiple processes in one chamber, such as lifftoff and stripping
- Prevention of chemicals attaching to water back-side
- Prevention of liquid and mist scattering
- Prevention of liquid and mist reattachment
- Efficent metal gathering
- Handling of thin and strained wafers

## Specifications

Applications		Lifftoff/Resist stripping/Polymer removing, cleaning		
Wafers	Materials	Si, Compounds( GaAs, InP, Sapphire, SiC, GaN ), etc.		
	Sizes	2, 3, 4, 5, 6, 8 inches ( two sizes can be used together )		
	optional apply	thin wafers and strained wafers		
Number of Processing Chambers		1	2	4
Scrubbing		High pressure jet/Atomizing jet/ultrasonic wave shower, etc.		
Processing Liquids		Organic stripper, Rinse agent, Pure water		
Supply System		Chemical circulation(with temp, control and filtration system)		
Conveyance Robot		Double-arm SCALAR robot		
Spin Chucks		Vacuum chuck / Mechanical chuck		
Alignment		Centerring / notch / orientation flat matching		
Dimensions (Main Unit)	Width (mm)	1,400	1,800	1,900
	Depth (mm)	2,100	2,200	2,900
	Height (mm)	2,200	2,200	2,200

## ◆ Consultation Service



Demonstration Machine

- We propose the ideal process based on the results of experiments performed our Technical Center.



Swelling



Stripping



Rinsing



Drying



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# Single Wafer Wet Processing System TWPm Series



- High stripping performance
- TAKADA proprietary jet-liftoff
- Compact design and reasonable price
- Ideal for R&D applications

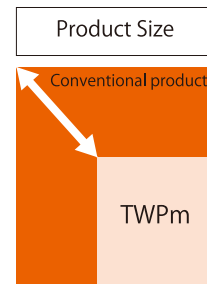
# TAKADA Wet Processor mini

## Applications

- ◆ Liftoff and resist stripping processes for MEMS, LED, high frequency devices
- ◆ Resist stripping and cleaning processes for WL-CSP advanced packaging

## Features

- **Small footprint**
  - ◆ Footprint... 2.9 m<sup>2</sup>→1.7 m<sup>2</sup> (40% reduction) ※compared with our conventional products
- **Maintenance-free back surface**
- **Performance functions carried over from TWP series**
  - ◆ Multiple processes in one chamber
  - ◆ Prevention of chemicals attaching to wafer back side
  - ◆ Prevention of liquid and mist scattering
  - ◆ Prevention of liquid and mist reattachment
  - ◆ Efficient metal gathering



## Specifications

Applications		Liftoff / Resist stripping / Polymer removing, cleaning
Wafers	Materials	Si, Compounds( GaAs, InP, Sapphire, SiC, GaN ), etc.
	Sizes	2 , 3 , 4 , 5 , 6 , 8 inches
Number of Processing Chambers		1
Processing Liquids(※optional)		Organic stripper, Pure water(※Rinse agent)
Scrubbing(※optional)		High pressure jet, (※atomizing jet, ultrasonic wave shower)
Supply System		Chemical circulation(with temp, control and filtration system)
Conveyance Robot		Original robot with centering function
Spin Chucks (※optional)		Vacuum chuck(※mechanical chuck)
Dimensions		1,200mm(W)×1,400mm(D)×2,000mm(H)

## ◆ Consultation Service

■ We propose the ideal process based on the results of experiments performed our Technical Center.

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